

“Concurrent effects of wafer temperature and oxygen fraction on cryogenic silicon etching with SF₆/O₂plasmas”. Tinck S, Tilocher T, Georgieva V, Dussart R, Neyts E, Bogaerts A, Plasma processes and polymers **14**, 1700018 (2017). <http://doi.org/10.1002/ppap.201700018>